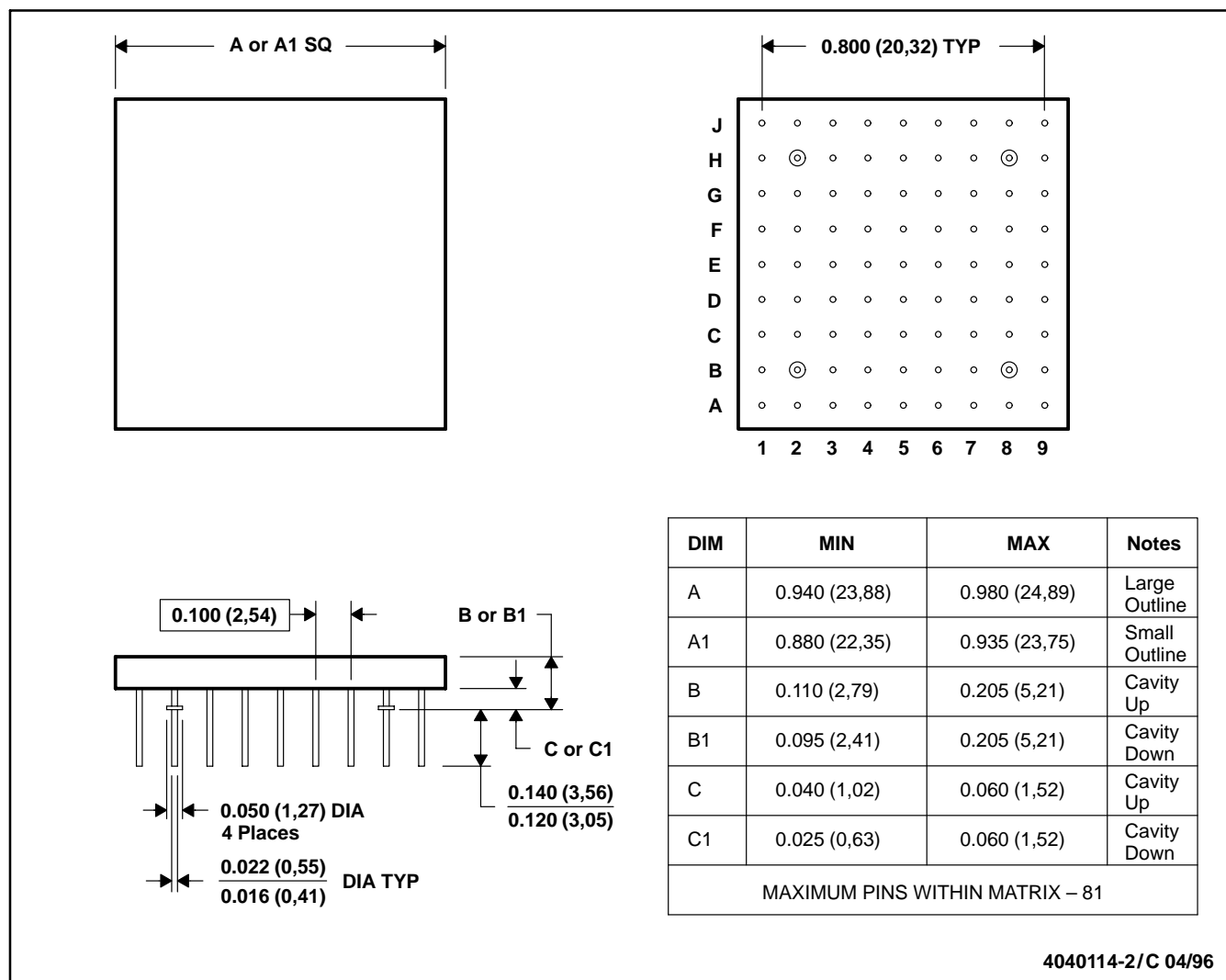


## GA-GB (S-CPGA-P9 X 9)

## CERAMIC PIN GRID ARRAY PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Index mark may appear on top or bottom depending on package vendor.
  - D. Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edge of the ceramic.
  - E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
  - F. The pins can be gold plated or solder dipped.
  - G. Falls within MIL-STD-1835 CMGA1-PN and CMGA13-PN and JEDEC MO-067AA and MO-066AA, respectively

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